Nch 60V 5.5A Power MOSFET

V _{DSS}	60V
R _{DS(on)} (Max.)	43mΩ
I _D	±5.5A
P _D	2.0W

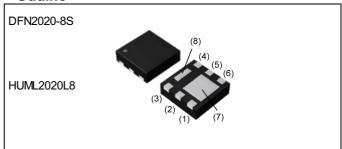
Features

- 1) Low on resistance
- 2) High Power small mold Package (HUML2020L8)
- 3) Pb-free lead plating; RoHS compliant
- 4) Halogen Free

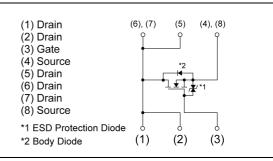
Application

Switching

Outline



●Inner circuit



Packaging specifications

	Packing	Embossed Tape
	Reel size (mm)	180
Туре	Tape width (mm)	8
	Basic ordering unit (pcs)	3000
	Taping code	TCR
	Marking	LA

● **Absolute maximum ratings** (T_a = 25°C ,unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain - Source voltage	V _{DSS}	60	V
Continuous drain current	I _D	±5.5	Α
Pulsed drain current	I _{DP} *1	±22	Α
Gate - Source voltage	V _{GSS}	±20	V
Avalanche current, single pulse	I _{AS} *2	3.5	Α
Avalanche energy, single pulse	E _{AS} *2	9.5	mJ
Power dissipation	P _D *3	2.0	W
Junction temperature	T _j	150	°C
Operating junction and storage temperature range	T _{stg}	-55 to +150	°C

●Thermal resistance

Parameter	Symbol	Values			Unit
raianetei	Symbol	Min.	Тур.	Max.	Offic
Thermal resistance, junction - ambient	R _{thJA} *3	-	-	62.5	°C/W

● Electrical characteristics (T_a = 25°C)

Parameter	Symbol	Conditions		Values		Unit	
Parameter	Symbol Conditions -		Min.	Тур.	Max.	Offic	
Drain - Source breakdown voltage	$V_{(BR)DSS}$ $V_{GS} = 0V, I_D = 1mA$		60	-	-	V	
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_{j}}$	I _D = 1mA referenced to 25°C	-	60	-	mV/°C	
Zero gate voltage drain current	I _{DSS}	V _{DS} = 60V, V _{GS} = 0V	-	-	1	μA	
Gate - Source leakage current	kage current I_{GSS} $V_{GS} = \pm 20V, V_{DS} = 0V$		ı	-	±10	μΑ	
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = 1mA$	1.3	-	2.7	V	
Gate threshold voltage temperature coefficient	$\frac{\Delta V_{GS(th)}}{\Delta T_j}$	I _D = 1mA referenced to 25°C	-	-5.6	-	mV/°C	
Static drain - source	D *4	V _{GS} = 10V, I _D = 5.5A	ı	31	43	mΩ	
on - state resistance	R _{DS(on)} *4	V _{GS} = 4.5V, I _D = 5.5A	-	43	66	1112	
Gate resistance	R _G f=1MHz, open drain		-	1.9	-	Ω	
Forward Transfer Admittance $ Y_{fs} ^*$		V _{DS} = 5V, I _D = 5.5A	5.0	-	-	S	

^{*1} Pw \leq 10 μ s, Duty cycle \leq 1%

^{*2} L \simeq 2mH, V_{DD} = 30V, R_G = 25 Ω , Starting T_i = 25 $^{\circ}$ C Fig.3-1,3-2

^{*3} Mounted on a Cu board (40×40×0.8mm)

^{*4} Pulsed

● Electrical characteristics (T_a = 25°C)

Davamatav	Symbol	Conditions	Values			Unit	
Parameter	Symbol Conditions —		Min.	Тур.	Max.	UIIIL	
Input capacitance	C _{iss}	V _{GS} = 0V	1	400	-		
Output capacitance	C _{oss}	V _{DS} = 30V	-	80	-	pF	
Reverse transfer capacitance	C _{rss}	f = 1MHz	-	20	-		
Turn - on delay time	t _{d(on)} *4	$V_{DD} \simeq 30V, V_{GS} = 10V$	-	9.2	-		
Rise time	t _r *4	I _D = 2.75A	1	17	-	no	
Turn - off delay time	$t_{d(off)}^{*4}$	R _L ~ 10.9Ω		23	-	ns	
Fall time	t _f *4	$R_G = 10\Omega$	-	21	-		

● Gate charge characteristics (T_a = 25°C)

Doromotor	Cumbal	Conditions		Values			l limit
Parameter	Symbol			Min.	Тур.	Max.	Unit
Total gate above	O *4		V _{GS} = 10V	-	7.8	-	
Total gate charge	Q _g *4	V _{DD} ≃ 30V		-	4.1	-	" C
Gate - Source charge	Q _{gs} *4	I _D = 5.5A	V _{GS} = 4.5V	-	1.7	-	nC
Gate - Drain charge	Q _{gd} *4			-	1.5	-	

● Body diode electrical characteristics (Source-Drain) (T_a = 25°C)

Doromotor	Symbol	Conditions	Values			Unit	
Parameter Symbol Conditions		Conditions	Min.	Тур.	Max.	Offic	
Continuous forward current	I _S	T = 25°C	-	-	1.67	Α	
Pulse forward current	I _{SP} *1	T _a = 25°C	-	-	22	Α	
Forward voltage	V _{SD} *4	V _{GS} = 0V, I _S = 1.67A	-	-	1.2	V	

Fig.1 Power Dissipation Derating Curve

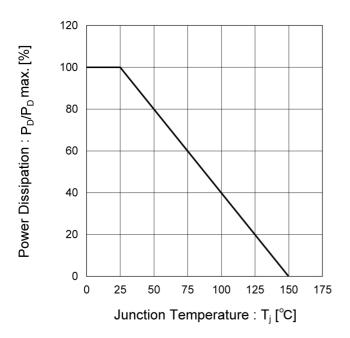
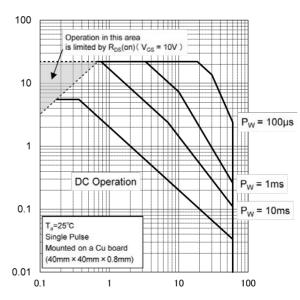


Fig.2 Maximum Safe Operating Area



Drain Current : I_D [A]

Drain - Source Voltage: V_{DS} [V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

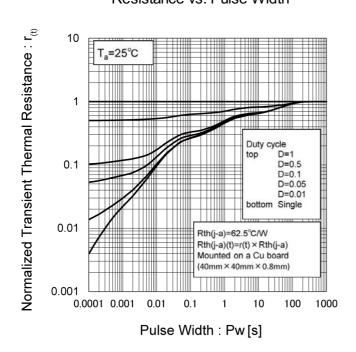


Fig.4 Single Pulse Maximum Power dissipation

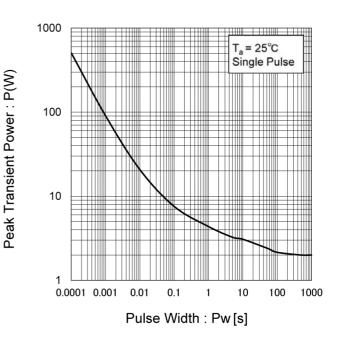


Fig.5 Typical Output Characteristics(I)

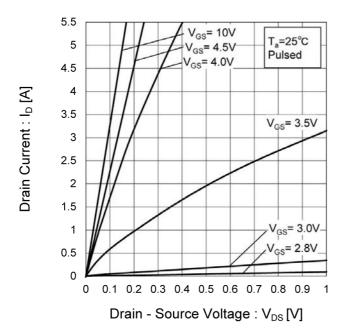


Fig.6 Typical Output Characteristics(II)

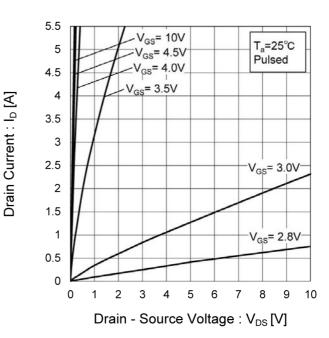


Fig.7 Breakdown Voltage vs.

Junction Temperature

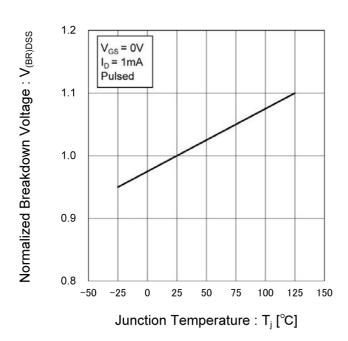


Fig.8 Typical Transfer Characteristics

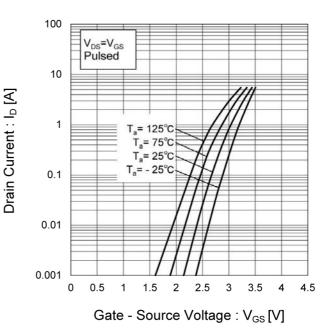


Fig.9 Gate Threshold Voltage vs.
Junction Temperature

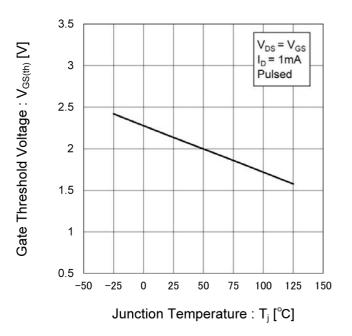


Fig.10 Forward Transfer Admittance vs.
Drain Current

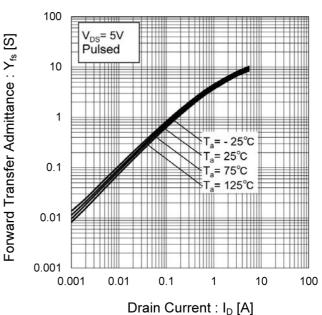


Fig.11 Drain Current Derating Curve

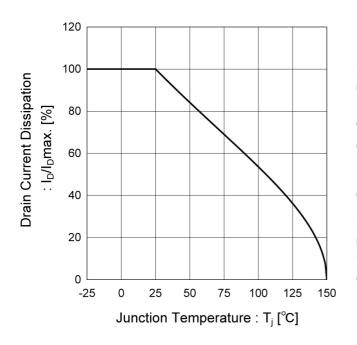


Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

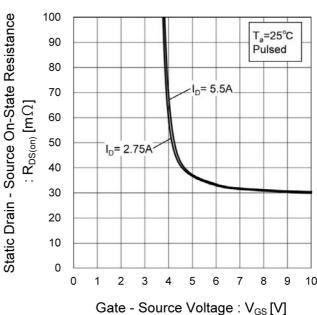


Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature

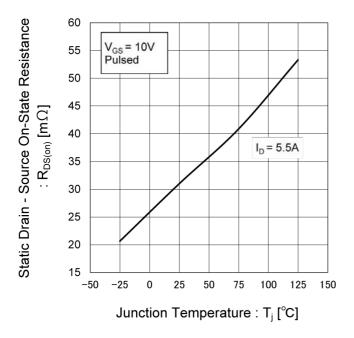


Fig.14 Static Drain - Source On - State
Resistance vs. Drain Current (I)

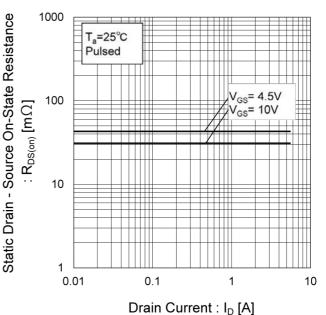


Fig.15 Static Drain - Source On - State Resistance vs. Drain Current (II)

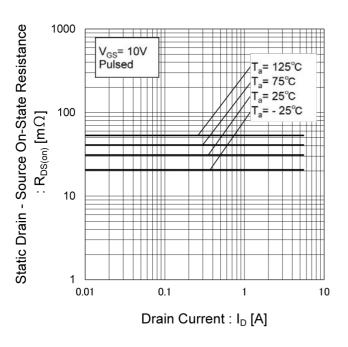


Fig.16 Static Drain - Source On - State Resistance vs. Drain Current (III)

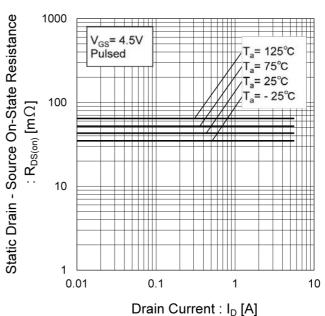
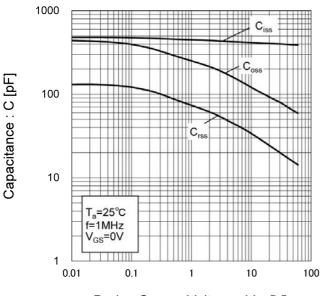


Fig.17 Typical Capacitance vs.

Drain - Source Voltage



Drain - Source Voltage : $V_{DS}[V]$

Fig.18 Switching Characteristics

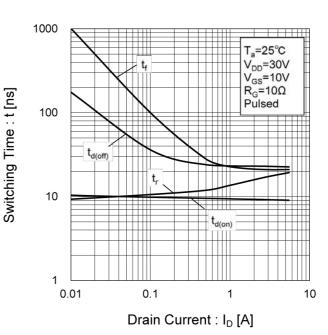


Fig.19 Dynamic Input Characteristics

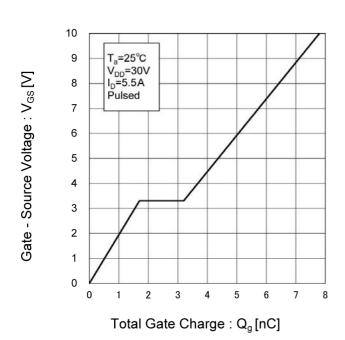
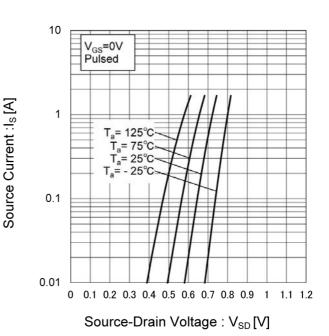


Fig.20 Source Current vs.
Source Drain Voltage



Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

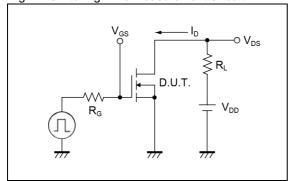


Fig.1-2 Switching Waveforms

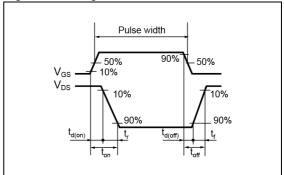


Fig.2-1 Gate Charge Measurement Circuit

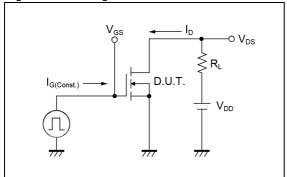


Fig.2-2 Gate Charge Waveform

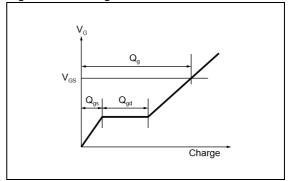


Fig.3-1 Avalanche Measurement Circuit

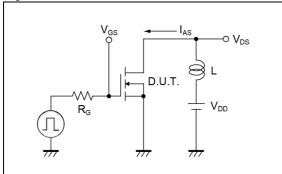
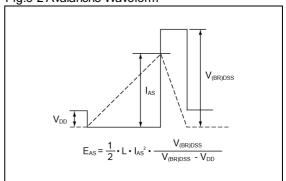


Fig.3-2 Avalanche Waveform

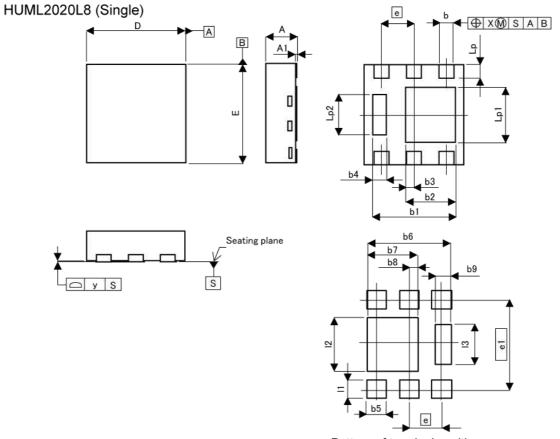


Notice

This product might cause chip aging and breakdown under the large electrified environment. Please consider to design ESD protection circuit.

Dimensions

DFN2020-8S



Pattern of terminal position areas [Not a pattern of soldering pads]

DIM	MILIME	TERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	0.55	0.65	0.022	0.026
A1	0.00	0.05	0.000	0.002
b	0.25	0.35	0.010	0.014
b1	1.55	1.75	0.061	0.069
b2	0.95	1.05	0.037	0.041
b3	0.1	75	0.007	
b4	0.25		0.0	10
D	1.90	2.10	0.075	0.083
E	1.90	2.10	0.075	0.083
е	0.60	0.70	0.024	0.028
Lp	0.225	0.325	0.009	0.013
Lp1	1.00	1.20	0.039	0.047
Lp2	0.80		0.031	
x		0.10		0.004
у	38.3	0.10	(80)	0.004

DIM	MILIMETERS		INCHES		
DIIVI	MIN	MAX	MIN	MAX	
b5	2 .0	0.45	o * -c	0.018	
b6	-	1.75	j. j.	0.069	
b7	9.	1.05		0.041	
b8	0.1	0.175		007	
b9	Sec. 1	0.30	9 0 0	0.012	
e1	1.5	1.725		068	
11		0.425	1.75	0.017	
12	:#L	1.15		0.045	
13	3	0.85) S 4 5	0.033	

Dimension in mm/inches



Notice

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JAPAN	USA	EU	CHINA
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CLASSIV	CLASSIII	CLASSIII	CLASSIII

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 - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

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- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

Precaution for Storage / Transportation

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
 may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
 exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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Notice-PGA-E Rev.003

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